



Microbond SOP® 91123 Anti – Capillary Solder Paste

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Anti - Capillary Solder Paste

The SOP 91123 Solder Pastes Series is a state of the art no clean lead free solder paste that promotes outstanding wetting.

The flux system is specifically optimized for lead free alloys such as the SAC series. This formula provides superior performance on a variety of surfaces and leaves a clear residue after reflow. The paste is developed as a halogen zero paste and therefore contains no halogens or halides.

Key Features:

- Halogen zero¹
- Excellent wetting under air & nitrogen
- Anti-Capillary effect beneath QFP & passive components
- Good high-volume print capability
- Minimizes soldering defects

¹ Halogen zero tolerance: < 50 ppm; measured according to BS EN 14582

Standard Product Specification:

- Lead free
- No clean classification
- RELO
- Halogen zero
- Powder size 20 – 38 µm / Type 4
- SAC 105; SAC 305; Innolot; Sn62

Version for High Reliability Applications:

SOP 91123 Innolot Solder Paste is a no clean solder paste developed for high reliability applications. The flux system is specifically optimized for lead free alloys, with a melting temperature above 200°C. This formula provides superior performance on a variety of surfaces finishes and leaves a clear residue after reflow.

SOP 91123 IL Solder Paste contains the Innolot alloy system, which adds bismuth (Bi), antimony (Sb) and nickel (Ni) to a SAC metallurgical system. The addition of these alloying elements allow operating temperatures as high as 150 to 165°C. Best results achieved under nitrogen atmosphere.



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